What is claimed is:

1. A sheet for sealing an electronic device, comprising:

a first surface having a surface roughness Ra of 0.3 μm or more; and

a second surface having a surface roughness Ra of 0.1 μm or less, wherein the second surface is a surface opposite to the first surface.

2. The sheet for sealing an electronic device according to claim 1,

wherein the first surface has a surface roughness Ra after thermal curing of 0.3 μm or more.

3. A method for manufacturing an electronic device package, the method comprising the steps of:

preparing a laminated body having an adherend and an electronic device fixed on the adherend with a bump interposed therebetween;

preparing the sheet for sealing an electronic device according to claim 1;

disposing the sheet for sealing an electronic device on the electronic device of the laminated body so that the second surface of the sheet for sealing an electronic device and the electronic device are brought into contact with each other;

embedding the electronic device into the sheet for sealing an electronic device by heat pressing; and

thermally curing the sheet for sealing an electronic device after the embedding step to obtain a sealed body.

4. The method for manufacturing an electronic device package according to claim 3,

wherein the first surface has a surface roughness Ra of 0.3 μm or more after the step of obtaining the sealed body.